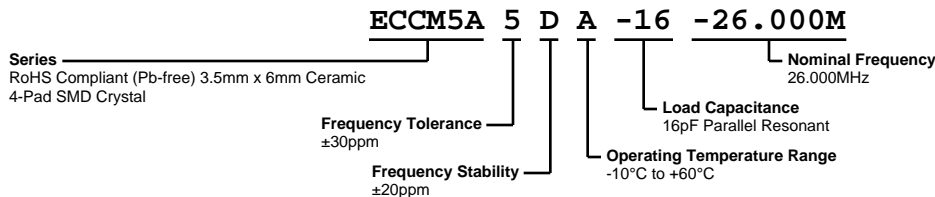


# ECCM5A5DA-16-26.000M



## ELECTRICAL SPECIFICATIONS

|                              |                                 |
|------------------------------|---------------------------------|
| Nominal Frequency            | 26.000MHz                       |
| Frequency Tolerance          | ±30ppm                          |
| Frequency Stability          | ±20ppm                          |
| Aging at 25°C                | ±3ppm/year Maximum              |
| Operating Temperature Range  | -10°C to +60°C                  |
| Load Capacitance             | 16pF Parallel Resonant          |
| Shunt Capacitance (C0)       | 5pF Maximum                     |
| Equivalent Series Resistance | 50 Ohms Maximum                 |
| Mode of Operation            | AT-Cut Fundamental              |
| Drive Level                  | 100µWatts Maximum               |
| Spurious Response            | -3dB Minimum; Fo to Fo +5000ppm |
| Storage Temperature Range    | -40°C to +85°C                  |
| Insulation Resistance        | 500 Megaohms Minimum at 100Vdc  |

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

|                              |   |
|------------------------------|---|
| ESD Susceptibility           | MIL-STD-883, Method 3015, Class 1, HBM: 1500V |
| Fine Leak Test               | MIL-STD-883, Method 1014, Condition A         |
| Flammability                 | UL94-V0                                       |
| Gross Leak Test              | MIL-STD-883, Method 1014, Condition C         |
| Mechanical Shock             | MIL-STD-883, Method 2002, Condition B         |
| Moisture Resistance          | MIL-STD-883, Method 1004                      |
| Moisture Sensitivity         | J-STD-020, MSL 1                              |
| Resistance to Soldering Heat | MIL-STD-202, Method 210, Condition K          |
| Resistance to Solvents       | MIL-STD-202, Method 215                       |
| Solderability                | MIL-STD-883, Method 2003                      |
| Temperature Cycling          | MIL-STD-883, Method 1010, Condition B         |
| Vibration                    | MIL-STD-883, Method 2007, Condition A         |

# ECCM5A5DA-16-26.000M

## MECHANICAL DIMENSIONS (all dimensions in millimeters)



| PIN | CONNECTION  |
|-----|-------------|
| 1   | Input       |
| 2   | Case/Ground |
| 3   | Output      |
| 4   | Case/Ground |

| LINE | MARKING  |
|------|--|
| 1    | <b>E26.00</b><br>E=Ecliptek Designator                     |
| 2    | <b>XXXXX</b><br>XXXXX=Ecliptek<br>Manufacturing Identifier |

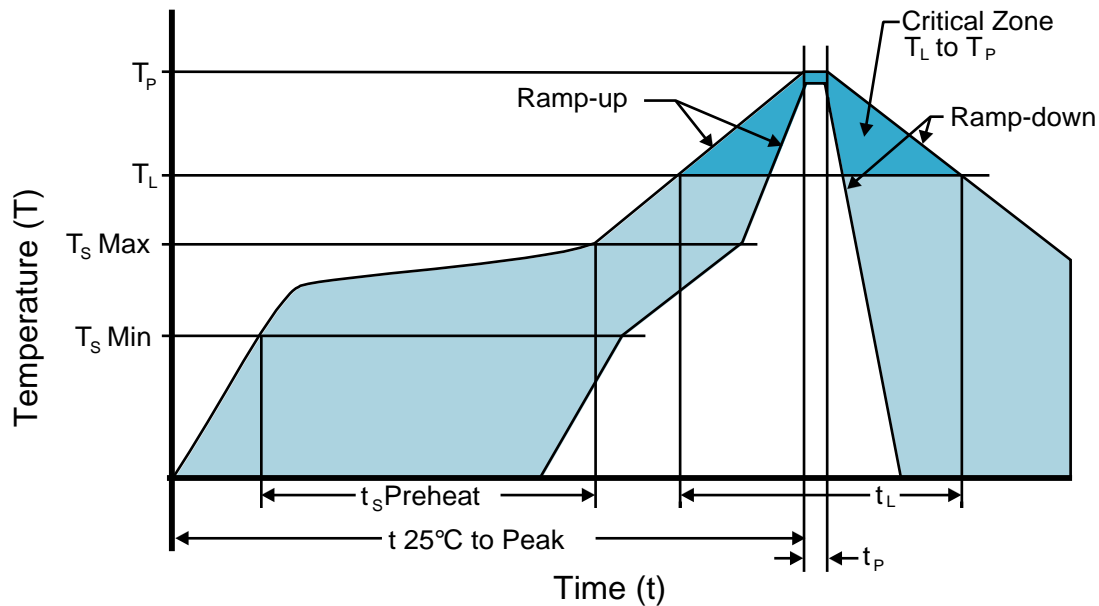
## Recommended Solder Reflow Methods



### High Temperature Infrared/Convection

|  |                                      |
|--|--------------------------------------|
| <b><math>T_s</math> MAX to <math>T_L</math> (Ramp-up Rate)</b> | 3°C/second Maximum                   |
| <b>Preheat</b>   |                                      |
| - Temperature Minimum ( $T_s$ MIN)                             | 150°C                                |
| - Temperature Typical ( $T_s$ TYP)                             | 175°C                                |
| - Temperature Maximum ( $T_s$ MAX)                             | 200°C                                |
| - Time ( $t_s$ MIN)  | 60 - 180 Seconds                     |
| <b>Ramp-up Rate (<math>T_L</math> to <math>T_p</math>)</b>     | 3°C/second Maximum                   |
| <b>Time Maintained Above:</b>                                  |                                      |
| - Temperature ( $T_L$ )  | 217°C                                |
| - Time ( $t_L$ )   | 60 - 150 Seconds                     |
| <b>Peak Temperature (<math>T_p</math>)</b>                     | 260°C Maximum for 10 Seconds Maximum |
| <b>Target Peak Temperature (<math>T_p</math> Target)</b>       | 250°C +0/-5°C                        |
| <b>Time within 5°C of actual peak (<math>t_p</math>)</b>       | 20 - 40 seconds                      |
| <b>Ramp-down Rate</b>  | 6°C/second Maximum                   |
| <b>Time 25°C to Peak Temperature (t)</b>                       | 8 minutes Maximum                    |
| <b>Moisture Sensitivity Level</b>                              | Level 1                              |

## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 245°C

|  |  |
|--|--|
| <b><math>T_S</math> MAX to <math>T_L</math> (Ramp-up Rate)</b> | 5°C/second Maximum                                     |
| <b>Preheat</b>   |  |
| - Temperature Minimum ( $T_S$ MIN)                             | N/A  |
| - Temperature Typical ( $T_S$ TYP)                             | 150°C  |
| - Temperature Maximum ( $T_S$ MAX)                             | N/A  |
| - Time ( $t_s$ MIN)  | 30 - 60 Seconds  |
| <b>Ramp-up Rate (<math>T_L</math> to <math>T_P</math>)</b>     | 5°C/second Maximum                                     |
| <b>Time Maintained Above:</b>                                  |  |
| - Temperature ( $T_L$ )  | 150°C  |
| - Time ( $t_L$ )   | 200 Seconds Maximum                                    |
| <b>Peak Temperature (<math>T_P</math>)</b>                     | 245°C Maximum  |
| <b>Target Peak Temperature (<math>T_P</math> Target)</b>       | 245°C Maximum 2 Times / 230°C Maximum 1 Time           |
| <b>Time within 5°C of actual peak (<math>t_p</math>)</b>       | 10 seconds Maximum 2 Times / 80 seconds Maximum 1 Time |
| <b>Ramp-down Rate</b>  | 5°C/second Maximum                                     |
| <b>Time 25°C to Peak Temperature (t)</b>                       | N/A  |
| <b>Moisture Sensitivity Level</b>                              | Level 1  |

### Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

### High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.